US00D567774S

(12) United States Design Patent

Tani et al.

(10) **Patent No.: US D567,774 S**

(45) **Date of Patent: ** Apr. 29, 2008**

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(54) **GROOVE FORMED AROUND A SEMICONDUCTOR DEVICE ON A CIRCUIT BOARD**

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(73) Assignee: **Nitto Denko Corporation**, Osaka (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/268,261**

(22) Filed: **Nov. 1, 2006**

(30) **Foreign Application Priority Data**

May 1, 2006	(JP)	2006-011443
May 1, 2006	(JP)	2006-011445
May 1, 2006	(JP)	2006-011446

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182; 174/250, 251, 253, 254, 255, 256, 265, 260, 174/261; 361/760, 748, 720; 336/200

See application file for complete search history.

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(57) CLAIM

The ornamental design for a groove formed around a semiconductor device on a circuit board, as shown and described.

DESCRIPTION

FIG. **1** shows a plan view of the groove formed around a semiconductor device on a circuit board showing our new design.

FIG. **2** shows an enlarged view of a claimed portion as identified by the area boxed by the dash-dot-dash line in FIG. **1**.

FIG. **3** shows an enlarged sectional view along the line **3**—**3** in FIG. **2**.

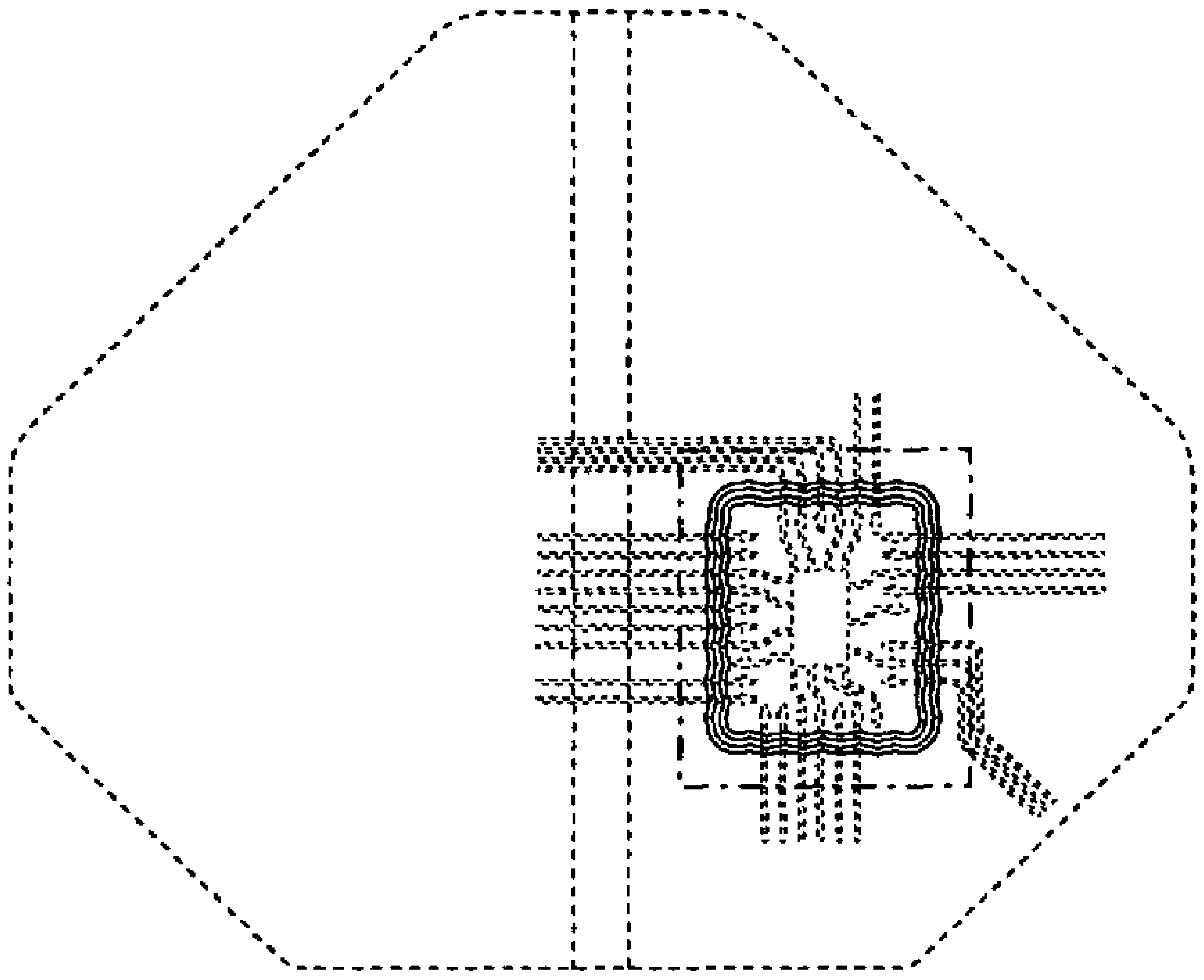
FIG. **4** shows an enlarged sectional view along the line **4**—**4** in FIG. **2**.

FIG. **5** shows a perspective view of the design in FIG. **1**; and,

FIG. **6** shows an enlarged sectional view along the line **4**—**4** in FIG. **2**, on which an environment semiconductor device is disposed.

The broken lines represent unclaimed subject matter.

1 Claim, 3 Drawing Sheets



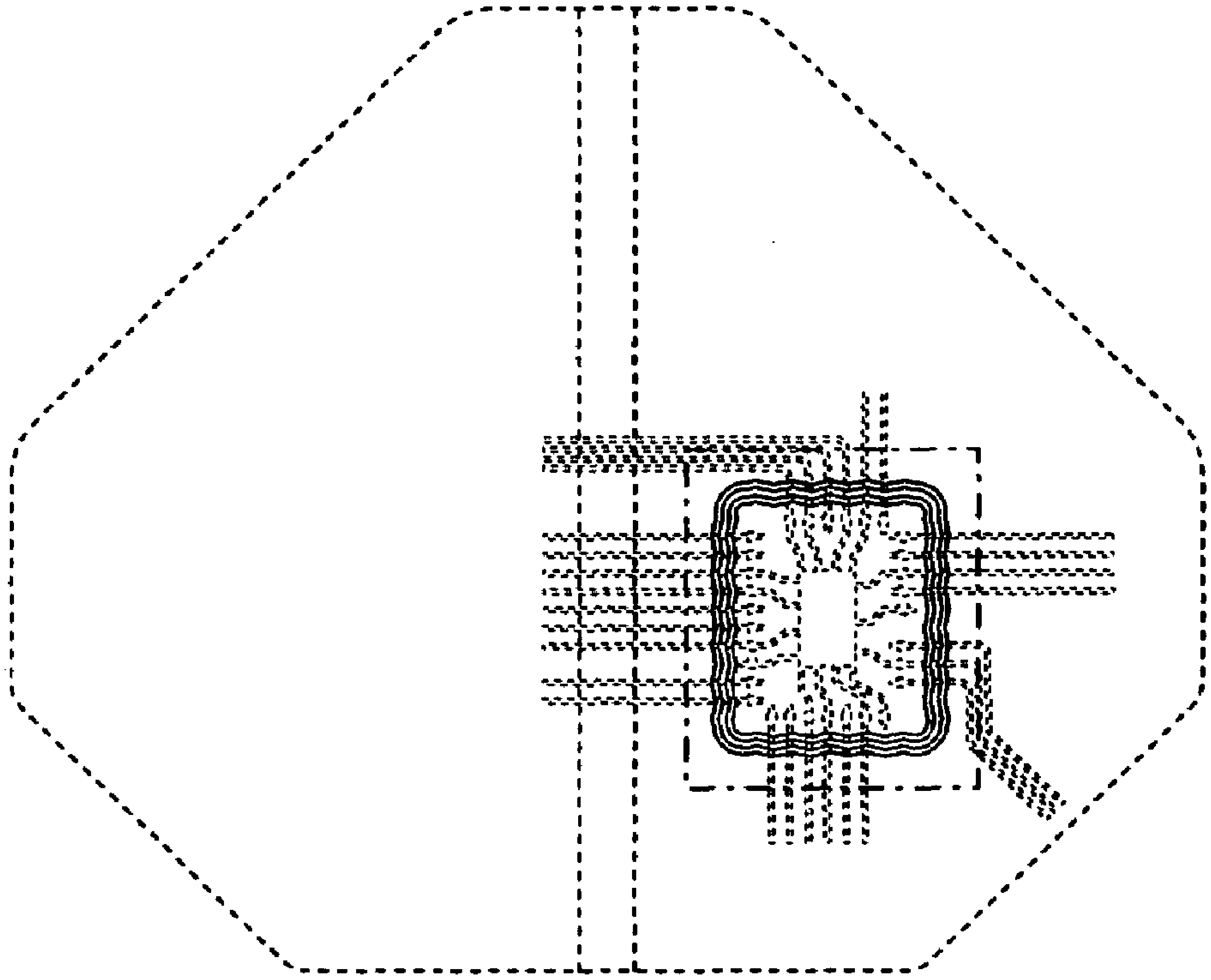


FIG. 1

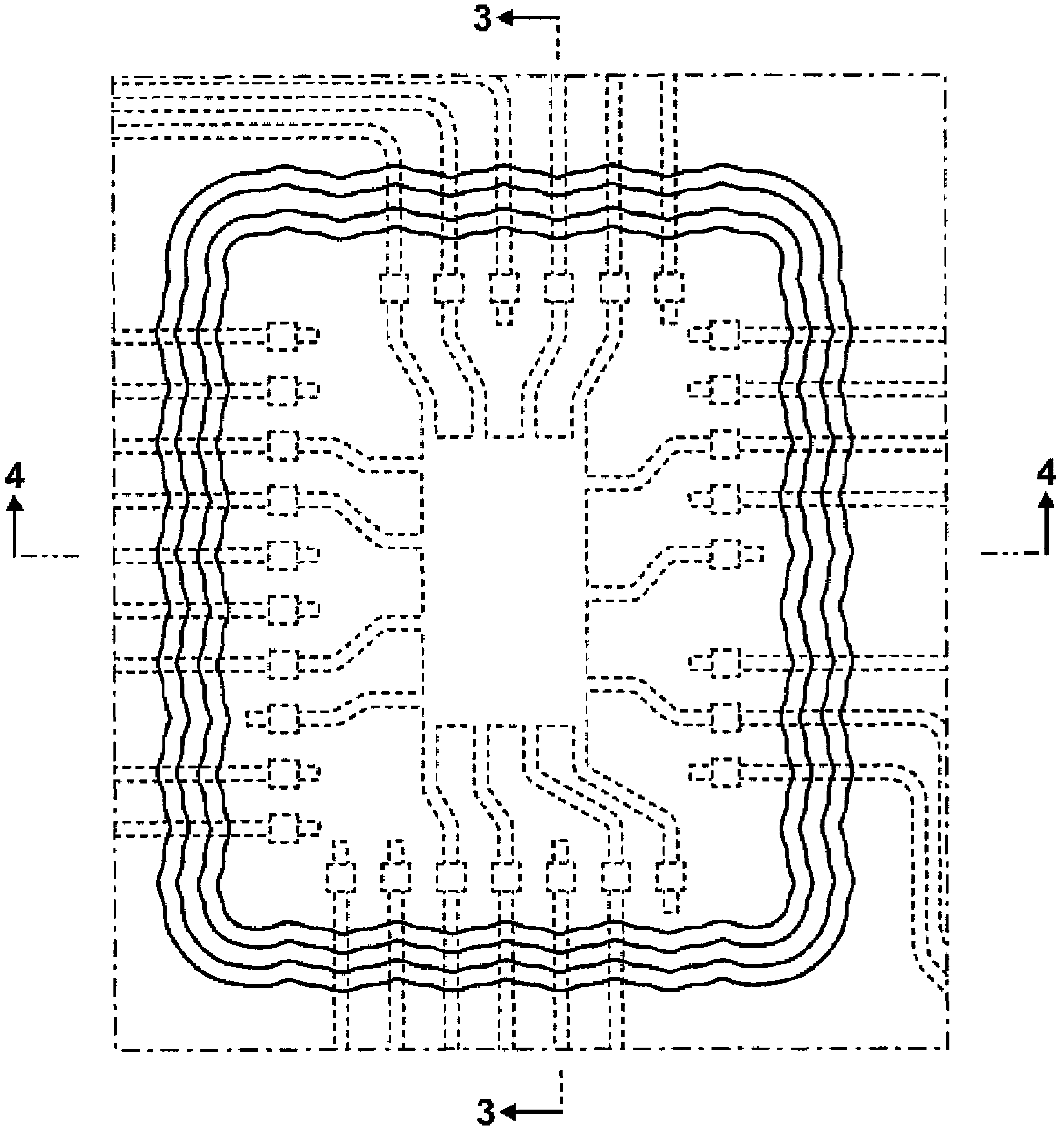


FIG. 2

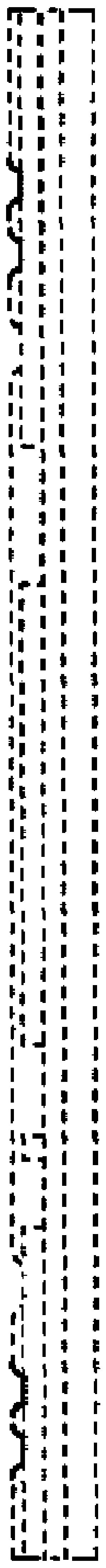


FIG. 3

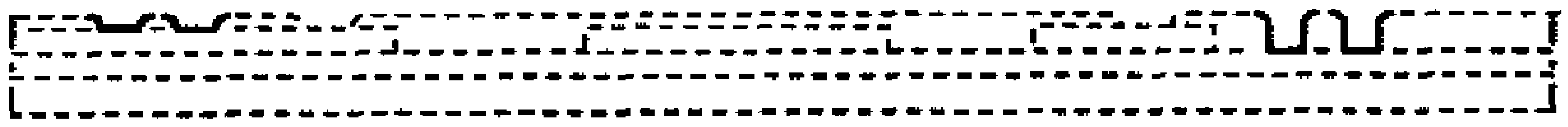


FIG. 4

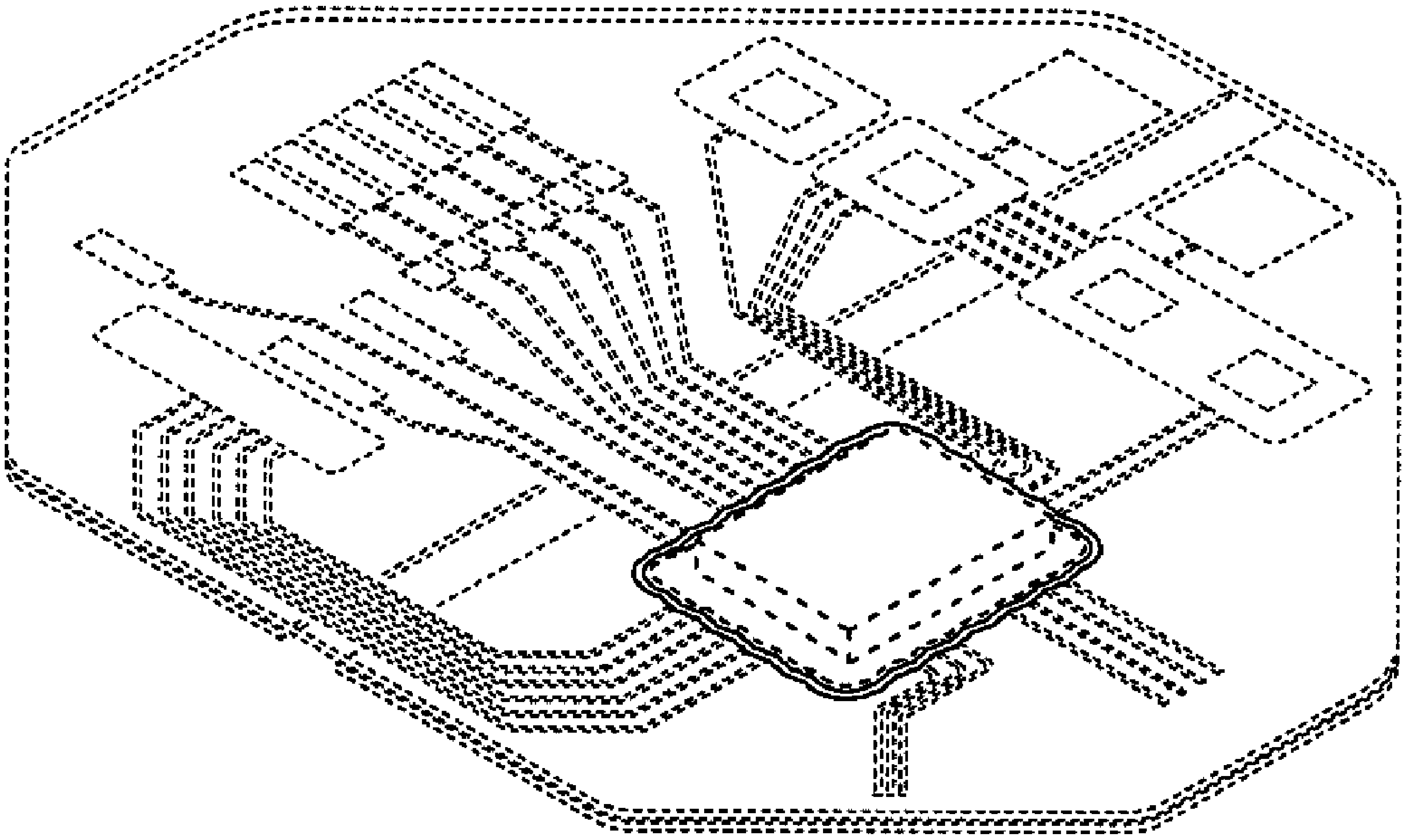


FIG. 5

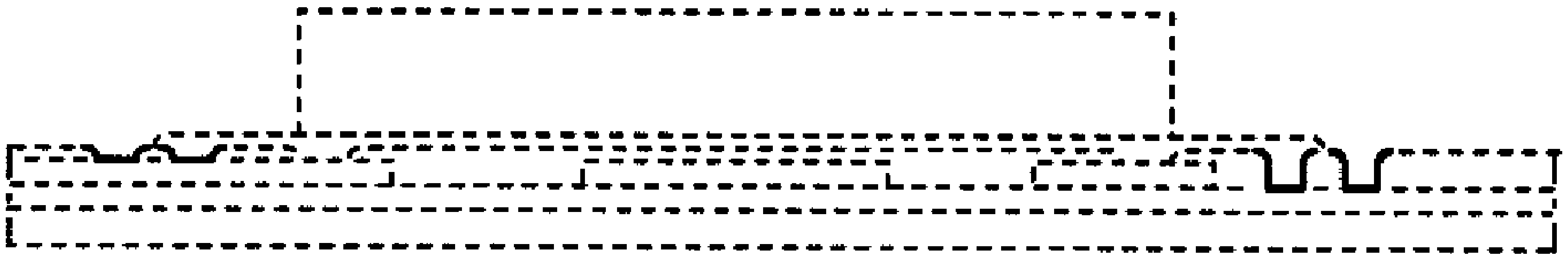


FIG. 6